

Ultra Precision SMT Resistor 1-2-3 Network

(Molded, J-Lead Terminal)





CONFIGURATION (DIMENSIONS IN mm)

RESISTANCE RANGE, TOLERANCE,

RAIED POWER								
Туре	Resistance Range Element**	Resistance Tolerance*		Rated Power/				
		Absolute*	Matching*	(W) at 125°C				
MU	10Ω ≤R <100Ω	±0.1% (B) ±0.5% (D)	±0.05% (A) ±0.1% (B) ±0.5% (D)					
	100Ω ≤R <1kΩ	±0.05% (A) ±0.1% (B) ±0.5% (D)	±0.02% (Q) ±0.05% (A) ±0.1% (B) ± 0.5% (D)	0.05				
	1kΩ ≤R ≤20kΩ	±0.02% (Q) ±0.05% (A) ±0.1% (B) ± 0.5% (D)	±0.01% (T) ±0.02% (Q) ±0.05% (A) ±0.1% (B) ±0.5% (D)					

Symbols in parentheses are for type number composition.

** Please contact us for the availability.

ABSOLUTE TO	CR	TCR TRACKING			
Resistance Range (Ω)	Absolute TCR (ppm/°C) -55C to +125°C	Resistance Ratio	TCR Track- ing (ppm/°C) –55°C to +125°C		
10Ω ≤R <30Ω	±15	Ratio = 1	±1		
30Ω ≤R <100Ω	±10	1 <ratio td="" ≤10<=""><td colspan="2">±2</td></ratio>	±2		
100Ω ≤R ≤20kΩ	100Ω ≤R ≤20kΩ ±5		±3		
		100 <ratio< td=""><td>±5</td></ratio<>	±5		

Applicable >50 Ω

FREQUENCY CHARACTERISTICS



EXAMPLE OF APPLICATIONS

An Application of Type MU (input/feedback resistors for amplifiers) Because the input and the feedback resistors are incorporated into one single element, amplification is not affected by temperature change.



Internal Circuit (Top View) PIN 2 com R Ra ≥ P2 Рз _P₃ PIN 1 PIN 3 W1 ŕ L2 ĩ W₃ W₃ Lз La W2 w н H₁ L H₂ Нз P1 P₂ P3 3.2 2.5 1.5 1.6 1.1 0.9 1.4 1.6 1.4 ±0.2 ±0.2 ±0.2 ±0.2 ±0.2 ±0.2 ±0.1 ±0.1 ±0.1 W1 W₂ Wз L1 L2 L3 L4 t 2.7 2.7 0.8 3.0 0.7 0.8 3.0 0.1 ±0.2 ±0.2 ±0.2 ±0.05 ±0.1 ± 0.2 ±0.2 ±0.1



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PERFORMANCE									
Parameters	Test Condition	ALPHA Specification		ALPHA Typical Test Data					
		ΔR	∆ Ratio	ΔR	Δ Ratio				
Maximum Rated Operating Temperature Working Temperature Range	num Rated Operating Temperature ng Temperature Range		125°C –65°C to +150°C						
Thermal Shock Overload	−65°C/30 min. \leftrightarrow +150°C/30 min., 5 cycles Rated Voltage x 2.5, 5 sec.	±0.05% ±0.05%	±0.02% ±0.02%	±0.01% ±0.01%	±0.005% ±0.005%				
Low Temperature Storage and Operation Substrate Bending Test	−65°C, No Load, 24 hrs. \rightarrow Rated Voltage, 45 min. 3 mm Bend 60 sec.	±0.05% ±0.05%	±0.02% ±0.02%	±0.01% ±0.01%	±0.005% ±0.005%				
Dielectric Withstanding Voltage	Atom. Pres.: AC 200V, 1 min. DC 100V, 1 min.	±0.01%	±0.01%	±0.005%	±0.0025%				
Insulation Resistance		over 10,000 MΩ		over 10,000 MΩ					
Resistance to Soldering Heat	260°C, 10 sec.	±0.05%	±0.02%	±0.01%	±0.005%				
Moisture Resistance	(240 hrs.)	±0.05%	±0.02%	±0.03%	±0.01%				
Shock	100G, 6 ms, Sawtooth Wave, X, Y, Z, each 10 shocks	±0.02%	±0.01%	±0.01%	±0.005%				
Vibration, High Frequency	20G, 10 Hz to 2,000 Hz to 10 Hz, 20 min., X, Y, Z, each 2.5 hrs.	±0.02%	±0.01%	±0.01%	±0.005%				
Life	125°C, Rated Power, 1.5 hrs. – ON, 0.5 hrs. – OFF, 2,000 hrs.	±0.05%	±0.02%	±0.03%	±0.015%				
Storage Life	e Life 15°C to 35°C, 15% RH to 75% RH, No Load, 10,000 hrs.		±0.0025%	±0.0025%	±0.0015%				
High Temperature Exposure	150°C, No Load, 2,000 hrs.	±0.05%	±0.02%	±0.02%	±0.01%				

TAPE AND REEL PACKAGE (BASED ON EIA-481-1) (DIMENSIONS IN mm)



PRECAUTION IN USING FACE-BONDED CHIP RESISTOR (DIMENSIONS IN mm)

Applicable

230

Not Applicable

5 10 20 30 40 50 60 (sec)

Length of contact

1. Storage

Storage condition or environment may adversely affect solderability of the exterior terminals. Do not store in high temperature and humidity. The recommended storage environment is lower than 40°C, has less than 70% RH humidity and is free from harmful gases such as sulphur and chlorine.

2. Caution in Soldering • Hand Soldering



- Recommended • Temp. of Iron Tip: 240°C to 270°C
- Power of Iron: 20W or less
- Diameter of Tip: Dia. 3 mm max.
- Solder Reflow in Furnace
- Recommended
- Peak Temperature: 250°C +0°C/-5°C
- Holding time: 10 sec. max.
- To cool gradually at room temperature
- Dipping in Solder (Wave or Still)
 Recommended
 - Temp. of Solder: 240°C to 250°C
 - Length of Dipping: 3 to 4 seconds
 - To cool gradually at room temperature

Other

Corrosion-free flux, such as rosin, is recommended. Do not apply pressure to the molded housing immediately after soldering.

3. Cleaning

Use volatile cleaner such as methylalcohol or propylalcohol. 4. Circuit Board Design

The dimensions of solder land must be determined in conformity with the size of resistors and with the soldering method. They are also subject to the mounting machine and the material of the substrate. See example below.



When parts are mounted on a board in high density, solder can possibly attach to the resistors in an excessive amount to affect performance or reliability of the resistors. To prevent this effect, the use of solder resist is recommended to isolate solder lands.

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